

determining the presence of a misalignment between the position of a TSV from the obverse side of the substrate and the position of the bottom end of the TSV within the substrate to identify a process excursion in a microfabrication process.

9. The method of characterizing a microfabrication process and a product formed by the microfabrication process of claim 8 further comprising the use of radiation in the near infrared range of wavelengths to obtain a position of the bottom end of the TSV's.